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SMT/Hybrid/Packaging 2010: SIPLACE continues its innovation drive

After the highly successful introduction of its SIPLACE SX1 and SX2 placement machines featuring swappable gantries (“Capacity-on-Demand”), Siemens Electronics Assembly Systems will unveil the new SIPLACE SX4 at the SMT/Hybrid/Packaging trade show in Nuremberg, Germany (June 6-8, 2010; Hall 7, Booth 204). As the flexible high-speed module of the SIPLACE SX-Series, the new machine shines with an astounding speed rating of 120,000 components per hour while taking up only 1.9 meters of line space, offering the perfect price-performance ratio especially for users in the flexible high-speed segment. As part of its Capacity-on-Demand concept, the SIPLACE team will also introduce its trailblazing “Peak Demand” and “Floating Demand” rent-a-gantry business models. In view of current economic developments, such concepts are becoming increasingly important for electronics manufacturers. The tutorial titled “Competitive Advantages of Build-to-Order in SMT Production”, which the SIPLACE team will host on June 6 as part of the SMT/Hybrid/Packaging Congress, will also be of great interest for electronics manufacturers. Using practical examples, SIPLACE will demonstrate during this event that build-to-order (BTO) is not a concept for the distant future, but that the necessary systems, methods and tools are available today. They will also learn how supplier integration, performance indicators, lean production or kanban concepts can be adapted to the specific requirements of SMT production.

The SMT/Hybrid/Packaging 2010 show will also see the European premier of the SIPLACE CA, the unique platform that makes it possible to place dies directly from the wafer using the standard SMT placement process. It also supports flip-chip as well as the die-attach (COB) processes.

SIPLACE will also present powerful software and service solutions for more transparent processes in all areas of SMT production. In combination with the SIPLACE SX line, these solutions provide the new basis for intelligent BTO strategies in the electronics industry.

“This year we will once again compete as the innovation leader with the SIPLACE SX4, which is the latest addition to the SIPLACE SX-Series, and the SIPLACE CA. Our new SIPLACE SX opens the door to a completely new range of manufacturing concepts that provide much more efficient solutions for ever-more-frequent product changeovers and massive demand fluctuations. The SIPLACE SX4 combines the extreme flexibility of the SX1 and SX2 with maximum speed. We now cover all the needs of our customers who want extreme scalability at an outstanding price-performance ratio,” says Ray Bruce, head of the global SIPLACE CRM organization.

Visitors can experience the latest SIPLACE innovations “live” in Nuremberg, Germany, at the SMT/HYBRID/PACKAGING, Hall 7, Booth 204.



At the SMT/Hybrid/Packaging the SIPLACE team will present the new SIPLACE SX4 and its trailblazing “Peak Demand” and “Floating Demand” rent-a-gantry business models.

For more information about SIPLACE, visit www.siplace.com.

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2 / 2

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